



PK464 (v1.0) March 4, 2011

# 100% Material Declaration Data Sheet FFG1924

**Average Weight: 25.0199 g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Silicon Die (FPGA)</b>				Silicon IC	<b>0.785000</b>	<b>3.138</b>
	Doped silicon (Si)	7440-21-3	100.00	Basis	0.785000	
<b>Solder Bump</b>				Die to package	<b>0.064920</b>	<b>0.259</b>
	Tin (Sn)	7440-31-5	63.00	Basis	0.040900	
	Lead (Pb)	7439-92-1	37.00	Basis	0.024020	
<b>Die Underfill</b>					<b>0.100000</b>	<b>0.400</b>
	Bisphenol F-type liquid epoxy resin	9003-36-5	20.00	Basis	0.020000	
	Phenolic resin	Trade secret	15.00	Basis	0.015000	
	Bisphenol A-type liquid epoxy resin	25068-38-6	5.00	Basis	0.005000	
	Amine type accelerator	Trade secret	5.00	Basis	0.005000	
	Silicon dioxide	60676-86-0	51.50	Basis	0.051500	
	Carbon black	1333-86-4	1.00	Basis	0.001000	
	Additives	Trade secret	2.50	Basis	0.002500	
<b>Solder Balls</b>					<b>1.610000</b>	<b>6.435</b>
	Tin (Sn)	7440-31-5	96.50	Base metal	1.553650	
	Silver (Ag)	7440-22-4	3.00	Base metal	0.048300	
	Copper (Cu)	7440-50-8	0.50	Base metal	0.008050	

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<b>Substrate</b>					<b>3.985534</b>	<b>15.929</b>
<b>Plating</b>	Copper (Cu)	7440-50-8	39.37	Main material	1.569075	
	Nickel (Ni)	7440-02-0	0.55	Main material	0.022095	
	Gold (Au)	7440-57-5	0.12	Main material	0.004787	
<b>Bump</b>	Lead (Pb)	7439-92-1	0.81	Main material	0.032301	
	Tin (Sn)	7440-31-5	1.38	Main material	0.054998	
<b>Copper Foil</b>	Copper (Cu)	7440-50-8	4.97	Main material	0.198108	
<b>Core</b>	Epoxy resin	N/A	5.55	Main material	0.221085	
	Copper (Cu)	7440-50-8	4.97	Main material	0.198108	
	Fiberglass	65997-17-3	18.49	Main material	0.736950	
<b>ABF</b>	Bisphenol A-type epoxy resin	25068-38-6	5.44	Main material	0.216750	
	Cyclohexane	108-94-1	5.44	Main material	0.216750	
	N, N-dimethylformamide	68-12-2	5.44	Main material	0.216750	
	Silica powder (Silicon dioxide)	7631-86-9	5.44	Main material	0.216750	
<b>Solder Mask</b>	Levelling agents & others	N/A	0.02	Main material	0.000648	
	Phthalocyanine blue, organic pigment	N/A	0.00	Main material	0.000162	
	Amine compound	N/A	0.01	Main material	0.000324	
	Barium sulfate	7727-43-7	0.28	Main material	0.011020	
	Silica	15468-32-3	0.14	Main material	0.005510	
	Talc	14807-96-6	0.14	Main material	0.005510	
	Diethylene glycol monoethyl ether acetate	N/A	0.07	Main material	0.002917	
	Dipropylane glycol monomethyl ether	N/A	0.06	Main material	0.002512	
	Dipropylane glycol monomethyl ether acetate	N/A	0.19	Main material	0.007373	
	High boiling-point petroleum solvent	N/A	0.15	Main material	0.006158	
	Aromatic carbonyl compound	N/A	0.05	Main material	0.002188	
	Acrylic monomer	N/A	0.07	Main material	0.002755	
	Acrylic resin	N/A	0.54	Main material	0.021634	
	Epoxy resin	N/A	0.31	Main material	0.012316	

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<b>Solder Paste</b>					<b>0.028400</b>	<b>0.114</b>
	Tin (Sn)	7440-31-5	96.50	Basis	0.027406	
	Silver (Ag)	7440-22-4	3.00	Basis	0.000852	
	Copper (Cu)	7440-50-8	0.50	Basis	0.000142	
<b>Capacitor</b>					<b>0.056000</b>	<b>0.224</b>
	Ceramic (BaTiO3 type)	Trade secret	61.80	Ceramic	0.034608	
	Inner electrode (Ni)	7440-02-0	27.00	Inner electrode	0.015120	
	Outer electrode (Cu)	7440-50-8	9.90	Outer electrode	0.005544	
	Plating1 (Ni)	7440-02-0	0.40	Plating1	0.000224	
	Plating2 (Sn)	7440-31-5	0.90	Plating2	0.000504	
<b>Capacitor</b>					<b>0.062400</b>	<b>0.249</b>
	Ceramic (BaTiO3 type)	Trade secret	67.40	Ceramic	0.042058	
	Inner electrode (Ni)	7440-02-0	17.00	Inner electrode	0.010608	
	Outer electrode (Cu)	7440-50-8	13.80	Outer electrode	0.008611	
	Plating1 (Ni)	7440-02-0	0.50	Plating1	0.000312	
	Plating2 (Sn)	7440-31-5	1.30	Plating2	0.000811	
<b>Capacitor</b>					<b>0.031200</b>	<b>0.125</b>
	Ceramic (BaTiO3 type)	Trade secret	64.94	Ceramic	0.020261	
	Inner electrode (Ni)	7440-02-0	19.20	Inner electrode	0.005990	
	Outer electrode (Cu)	7440-50-8	14.07	Outer electrode	0.004390	
	Plating1 (Ni)	7440-02-0	0.51	Plating1	0.000159	
	Plating2 (Sn)	7440-31-5	1.28	Plating2	0.000399	
<b>Capacitor</b>					<b>0.008400</b>	<b>0.034</b>
	Ceramic (BaTiO3 type)	Trade secret	66.00	Ceramic	0.005544	
	Inner electrode (Ni)	7440-02-0	2.67	Inner electrode	0.000224	
	Outer electrode (Cu)	7440-50-8	23.33	Outer electrode	0.001960	
	Plating1 (Ni)	7440-02-0	2.33	Plating1	0.000196	
	Plating2 (Sn)	7440-31-5	5.67	Plating2	0.000476	
<b>Heat Sink</b>					<b>18.108000</b>	<b>72.375</b>
	Copper (Cu)	7440-50-8	99.15	Main material	17.954082	
	Nickel (Ni)	7440-02-0	0.85	Main material	0.153918	
<b>Heat Sink Adhesive</b>					<b>0.180000</b>	<b>0.719</b>
	Aluminum oxide	1344-28-1	70.00	Main material	0.126000	
	Zinc oxide	1314-13-2	15.00	Main material	0.027000	
	Organic Silicon compound	Trade secret	15.00	Main material	0.027000	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/04/11	1.0	Initial Xilinx release.

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